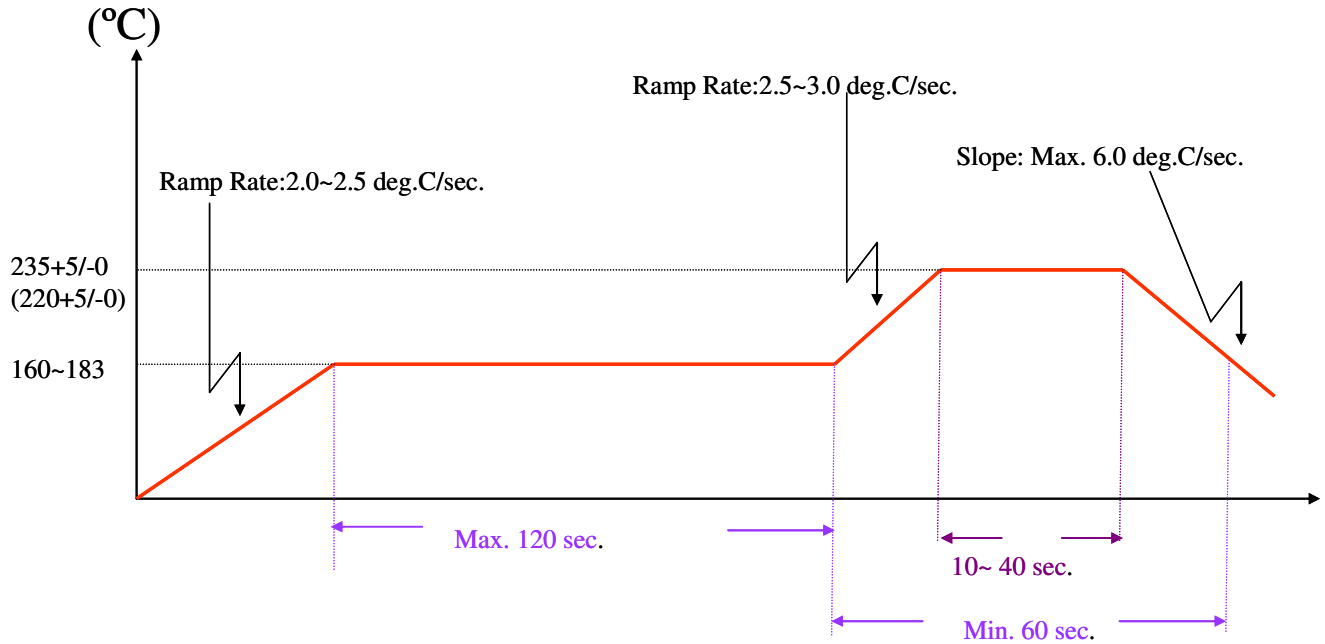


### Lead Frame Packages Soldering Re-flow Profile



Note:

1. The peak temperature 220+5/-0 deg. C will be performed when package met the requirement that thickness > 2.5 mm, or package thickness < 2.5 mm and package volume > 350 mm<sup>3</sup>.
2. The peak temperature 235+5/-0 deg. C will be performed when package met the requirement that thickness < 2.5 mm and package volume < 350 mm<sup>3</sup>.